

Chip Scale Review

2019 Editorial Calendar

(Editorial close date: 12/1/2018)

January • February

Industry Events * indicates show distribution

New test methodologies for 5G
RF/OTA
Thermal debonding and warpage in FOWLP
W2W/D2W & other bonding advances for 3D ICs
Temporary bonding & the challenges of cleaning post debond
Discontinuities drive data integration
IC packaging for Moore's Law
Heterogeneous integration
Thin wafer handling

- SMTA Pan Pac Microelectronics Symposium
Kauai, Hawaii (Feb 11-14)
- **FLEX / MEMS & Sensors Technical Congress ***
Monterey, CA (Feb 18-21)
- **TestConX ***
Mesa, AZ (March 3-6)
- IMAPS Device Packaging
Fountain Hills, AZ (March 4-7)
- SEMI-THERM
San Jose, CA (March 18-22)
- SEMICON China
Shanghai, China (March 20-22)
- **ISS Europe**
Milan, Italy (March 31-April 2)

Ad Space Close Jan 18 - Ad Materials Close Jan 25

(Editorial close date: 2/28/19)

March • April

Industry Events * indicates show distribution

Power devices
Packaging of implantable devices
Silicone surface contamination for optimizing package assembly
Electroplating models for 3D TSVs
Failure relief in WLP & PLP polymer layers
Automotive IC production wafer test in a zero-defect world
Testing of HF 5G applications and why simulations are critical to success
High-density and high-bandwidth C2C connections

- ASMC 2019
Saratoga Springs, NY USA (May 6-9)
- SEMICON SE Asia
Kuala Lumpur, Malaysia (May 7-9)
- Meptec/SMTA Medical Electronics Symposium
Elyria, OH USA (May 20-21)
- **ECTC ***
Las Vegas, NV USA (May 28-31)
- IEEE/SW Test Workshop (SWTW)
San Diego, CA (June 2-5)

Ad Space Close Mar 15 - Materials Close Mar 22

(Editorial close date: 4/15)

May • June

Industry Events * indicates show distribution

Automotive packaging
Market drivers in automotive
SoCs for automotive
Driving reliability in automotive electronics assembly materials
Dispensed materials for additive manufacturing
Wafer scribing/dicing
Exposed die FOWLP by transfer molding
Inspection and metrology challenges
Multi-functional adhesives
Stretchable interconnects

- Sensors Expo
San Jose, CA USA (June 25-27)
- **SEMICON West**
San Francisco, CA USA (July 9-11)

International Directory of Wafer Dicing & Scribing Systems

Ad Space Close May 10 - Ad Materials Close May 17

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